## **SPECIFICATION**

## **OF PRODUCTS**

CUSTOMER : _	RS Components
PRODUCT NAME: _	CERAMIC RESONATOR
PART NUMBER :	117-ZTACS12.00MTF-W

Approved by	Checked by	Drawn by

## **Interquip Electronics Co Ltd.**

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Part Number Sheet		
Customer		
Supplier P/N	117-ZTACS12.00MTF-W	
Customer P/N		

Customer's Approval Certificate		
Checked & Approval by		
Date		

Mark Of Modification	Reason Of Modification	Modification	Drawn	Checked	Approval	Date

Please return this copy after signing as a certification of your approval.

### 1. SCOPE

This specification shall cover the characteristics of the ceramic resonator with the type 117-ZTACS12. 00MTF-W.

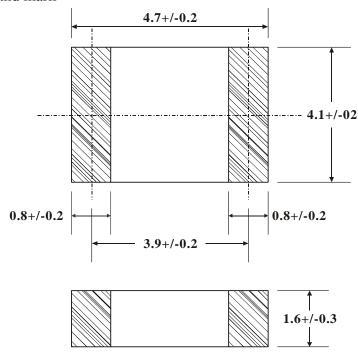
### 2. PART NO.

PART NUMBER
117-ZTACS12. 00MTF-W
CUSTOMER PART NO

### 3. OUTLINE DIMENSIONS AND MARK

- 3.1 Appearance: No visible damage and dirt.
- 3.2 Construction: SMD ceramic packaging.
- 3.3 The products conform to the RoHS directive and national environment protection law.

### 3.4 Dimensions and mark



### 4. ELECTRICAL SPECIFICATIONS

### 4.1 RATING

Items	Requirement	
Withstanding Voltage (V)	50 (DC, 1min)	
Insulation Resistance Ri, (M \Omega) min.	100 (10V, 1min)	
Operating temperature	-25℃~85℃	
Storage temperature	-55℃~85℃	
Rating Voltage U <sub>R</sub> (V)	6V DC	
Kating voitage Or (V)	15V p-p	

### **4.2 ELECTRICAL SPECIFICATIONS**

Items	Requirement
Oscillation Frequency Fosc (MHz)	12.000
Frequency Accuracy (%)	±0.5
Resonant Impedance Ro $(\Omega)$ max.	30
Temperature Coefficient of Oscillation	$\pm 0.3$ (Oscillation Frequency
Frequency (%) max.	drift, -25°C∼+85°C)
Oscillation Frequency	$\pm 0.3$ (From initial value)
Aging Rate (%) max *	

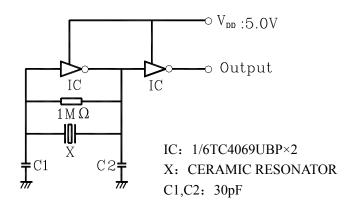
<sup>\*</sup> Components shall be left in a chamber of  $+85\pm2^{\circ}$ C for 1000 hours, then measured after leaving in natural condition for 1 hours.

### 5. TEST

### 5.1 Test Conditions

Parts shall be tested under the condition ( Temp.:  $20\pm15\,^{\circ}$ C, Humidity :  $65\pm20\%$  R.H.) unless the standard condition(Temp.:  $25\pm2\,^{\circ}$ C, Humidity :  $65\pm5\%$  R.H.) is regulated to measure.

### 5.2 Test Circuit



### 6 PHYSICAL AND ENVIRONMENTAL CHARACTERISTICS

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No	Item	Conditio	Performance	
		TZ 11 1 1 1 1	Requirements	
		Keep the resonator at 40	It shall fulfill	
6.1	Humidity	RH for 96h. Then Rel	the	
	,		for 1h prior to the	specifications
		Measurement.		in Table 1.
	High	Subject the resonator	to 85°C±5°C for 96h,	It shall fulfill
6.2	Temperature	then release the reso	onator into the room	the
	Exposure	conditions for 1h prior t	to the measurement.	specifications
	1	-		in Table 1.
	Low	Subject the resonator	to -55°C±5°C for 96h,	It shall fulfill
6.3	Temperature	then release the reso	onator into the room	the
	Exposure	conditions for 1h prior t	to the measurement.	specifications
	-			in Table 1.
		1	ing of blow table was	
		_	nator shall be measured	It shall fulfill
6.4	Temperature	after being placed in nat	tural conditions for 1h.	the
0.1	Cycling	Temperature	Time	specifications
		-25±3°C	$30\pm3$ min	in Table 1.
		85±3℃	$30\pm3$ min	
		Subject the resonator to	vibration for 2h each in	It shall fulfill
6.5	Vibration	x, y and z axis With the	ne amplitude of 1.5mm,	the
0.3	Vibration	the frequency shall	be varied uniformly	specifications
		between the limits of 10	Hz—55Hz.	in Table 1.
				It shall fulfill
6.6	Mechanical	Drop the resonator rar	ndomly onto a wooden	the
0.0	Shock	floor from the height of	100cm 3 times.	specifications
				in Table 1.
		Passed through the re		
		following condition		
		temperature for 1h before	re measurement.	
		Deals 0/080 as	10s max	
		Peak: 260°⊜ ma	x 250°C	It shall fulfill
6.7	Soldering	230°C		the
	Test	///////////////////////////////////////		specifications
		150°C		in Table 1.
		100°C Pre-heating		
		100		
		within	within	
		30s min 80-120s.	20-40s	

(To be continued)

### 6 PHYSICAL AND ENVIRONMENAL CHARACTERISICS

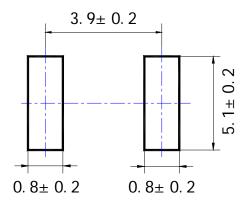
No	Item	Condition of Test	Performance Requirements
6.8	Solder Ability	Dipped in 245 °C ±5 °C solder bath for $3s\pm0.5$ s with rosin flux (25wt% ethanol solution.)	The terminals shall be at least 95% covered by solder.
6.9	Board Bending	Mount a glass-epoxy board (Width=40mm,thickness=1.6mm),then bend it to 1mm displacement and keep it for 5s. (See the following figure)  PRESS  PRESS HEAD  D.U.T.  O  HESS  SUPPORT BAR	Mechanical damage such as breaks shall not occur.

Table 1

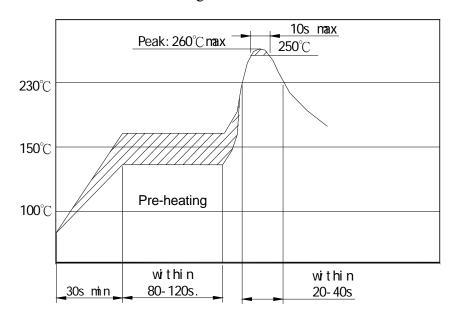
Item	Specification after test	
Oscillation Frequency Change  \$\Delta\$ fosc/fosc (%) max.	±0.3	
Resonant Impedance Ro $(\Omega)$ max.	35	
The limits in the above table are referenced to the initial measurements.		

## 7 RECOMMENDED LAND PATTERN AND REFLOW SOLDERING STANDARD CONDITIONS

### 7.1Recommended land pattern



### 7.2Recommended reflow soldering standard conditions

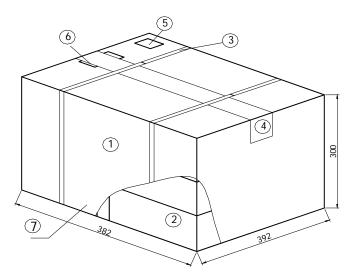


## 8. PACKAGE

To protect the products in storage and transportation, it is necessary to pack them (outer and inner package).

8.1 On paper pack, the following requirements are requested.

### 8.1.1 Dimensions and Mark



NO.	Name	Quantity
1	Package	1
2	Inner Box	12
3	Belt	2.9 m
4	Adhesive tape	1.2 m
(5)	Label	1
6	Certificate of approval	1
7	Company name ,Address etc.	

## 8.1.2 Section of package

Package is made of corrugated paper with thickness of 0.8cm.Package has 12 inner boxes, each box has 5reels(each reel for plastic bag)

### 8.1.3 Quantity of package

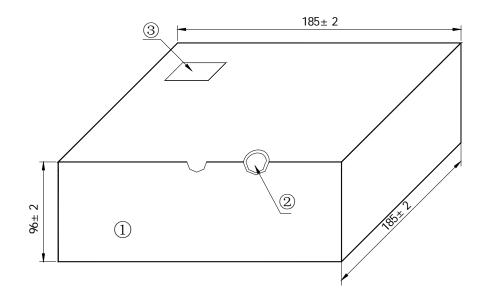
Per plastic reel 1000 pieces of piezoelectric ceramic part

Per inner box 5 reels

Per package 12 inner boxes

(60000 pieces of piezoelectric ceramic part )

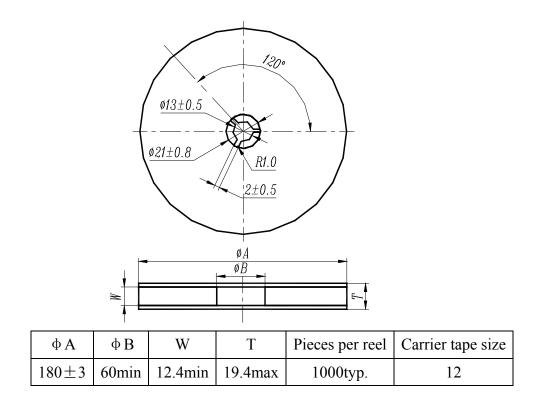
### 8.1.4 Inner Box Dimensions



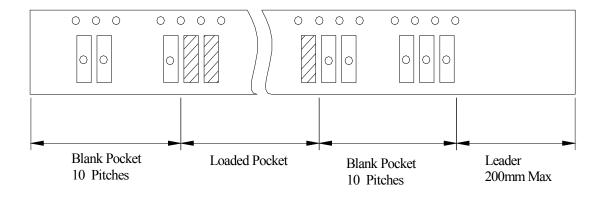
NO.	Name	Quantity
1)	Inner Box	1
2	QC Label	1
3	Label	1

8.2 On reel pack, the following requirements are requested.

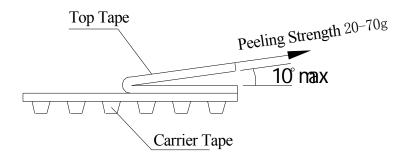
### 8.2.1 Reel Dimensions



## 8.2.3 Packing Method Sketch Map



# INTERQUIP ELECTRONICS CO LTD 8.2.4Test Condition Of Peeling Strength



## 9. EIAJ Monthly Code

2005 / 2007 / 2009		2006 / 2008 / 2010	
MONTH	CODE	MONTH	CODE
JAN	A	JAN	N
FEB	В	FEB	P
MAR	С	MAR	Q
APR	D	APR	R
MAY	Е	MAY	S
JUN	F	JUN	T
JUL	G	JUL	U
AUG	Н	AUG	V
SEP	J	SEP	W
OCT	K	OCT	X
NOV	L	NOV	Y
DEC	M	DEC	Z

- 10. OTHER
- 10.1 Caution
- 10.1.1 Don't apply excess mechanical stress to the component and terminals at soldering. Do not use this product with bend.
- 10.1.2 Do not clean or wash the component for it is not hermetically sealed.
- 10.1.3 Do not use strong acidity flux, more than 0.2wt% chlorine content, in flow soldering.
- 10.1.4 Don't be close to fire.
- 10.1.5 This specification mentions the quality of the component as a single unit. Please insure the component is thoroughly evaluated in your application circuit
- 10.1.6 Expire date (Shelf life) of the products is six months after delivery under the conditions of a sealed and an unopened package. Please use the products within six months after delivery. If you store the products for a long time (more than six months), use carefully because the products may be degraded in the solderability or rusty. Please confirm solderability and characteristics for the products regularly.
- 10.1.7 Please contact us before using the product as automobile electronic component.
- 10.2 Notice
- 10.2.1 Please return one of these specifications after your signature of acceptance.
- 10.2.2 When something gets doubtful with this specification, we shall jointly work to get an agreement